

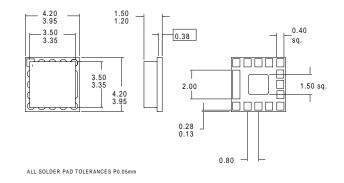
1900MHZ 3V POWER AMPLIFIER

Typical Applications

- PACS Handsets and Base Stations
- 3V 1850-1910MHz CDMA PCS Handsets
- 3V 1750-1780MHz CDMA PCS Handsets
- 3V TDMA PCS Handsets
- Spread-Spectrum Systems
- Commercial and Consumer Systems

Product Description

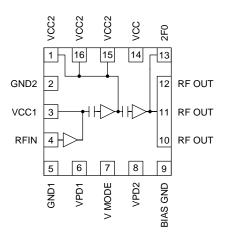
The RF2153 is a high-power, high-efficiency linear amplifier IC targeting 3V handheld systems. The device is manufactured on an advanced Gallium Arsenide Heterojunction Bipolar Transistor (HBT) process, and has been designed for use as the final RF amplifier in 3V CDMA and TDMA handheld digital equipment, spread-spectrum systems, and other applications in the 1750MHz to 1910 MHz band. The device is packaged in a compact 4mmx4mm (LCC). The device's frequency response can be optimized for linear performance in the 1750MHz to 1910MHz band.



Optimum Technology Matching® Applied

Si BJT

GaAs HBT ☐ GaAs MESFET ☐ SiGe HBT ☐ Si CMOS



Functional Block Diagram

Package Style: MP16K01A

Features

- Single 3V Supply
- 29dBm Linear Output Power
- 30dB Linear Gain
- 33% Linear Efficiency CDMA
- 40% Linear Efficiency TDMA
- On-board Power Down Mode

Ordering Information RF2153 CDMA/TDMA/PACS 1900MHz 3V Power Amplifier RF2153 PCBA Fully Assembled Evaluation Board

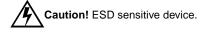
 RF Micro Devices, Inc.
 Tel (336) 664 1233

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 Greensboro, NC 27409, USA
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Absolute Maximum Ratings

Parameter	Rating	Unit
Supply Voltage (RF off)	+8.0	V _{DC}
Supply Voltage (P _{OUT} ≤31dBm)	+4.5	V _{DC}
Mode Voltage (V _{MODE})	+3.5	V _{DC}
Control Voltage (V _{PD})	+3.5	V _{DC}
Input RF Power	+10	dBm
Operating Case Temperature	-30 to +110	°C
Storage Temperature	-30 to +150	°C

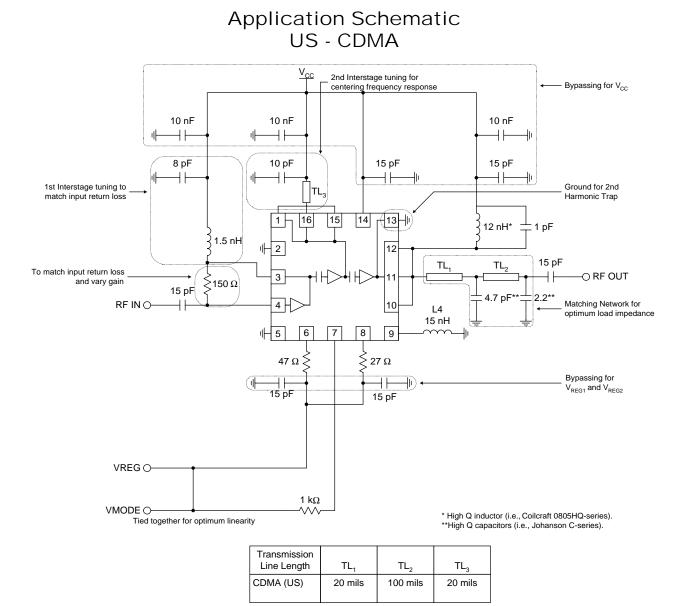


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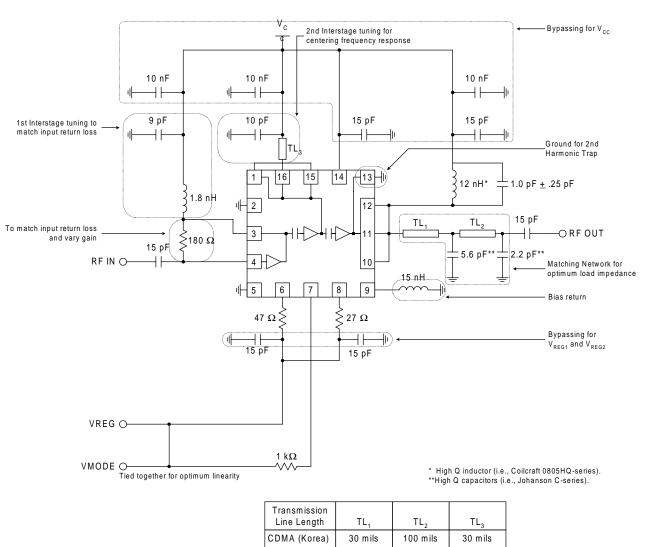
Parameter	:	Specification	Ì	Unit	Condition
Falailletei	Min.	Тур.	Max.	Unit	Condition
Overall - CDMA					T=25°C, V _{CC} =3.4V unless otherwise speci-
Usable Frequency Range	1750		1910	MHz	fied
Typical Frequency Range		1750-1780		MHz	Output Matching Network Tune
	00	1850-1910	0.4	MHz	Output Matching Network Tune
Small Signal Gain	30	32	34	dB	V _{MODE} =Low 0V to 0.5V
	26	29			V _{MODE} =High 2.5V to 3.0V
Linear Gain	26	29		dB	V _{MODE} =High 2.5V to 3V
					P_{OUT} =29dBm, V_{CC} =3.4V, V_{REG} =2.8V
Second Harmonic (including second harmonic trap)		-35		dBc	
Third Harmonic		-40		dBc	
Fourth Harmonic		-45		dBc	
Minimum Linear Output Power (CDMA or TDMA Modulation)	29			dBm	
Idle Current	90	100	200	mA	V _{MODE} =>2.5V
CDMA Linear Efficiency	30	33			P _{OUT} =29dBm, V _{CC} =3.4V, V _{REG} =2.8V
CDMA Adjacent Channel Power Rejection @ 1.25MHz		-46	-44	dBc	P_{OUT} =29dBm, V_{CC} =3.4V, V_{REG} =2.8V
Minimum Linear Output Power (CDMA Modulation)	28	+29		dBm	V _{CC} =3.0V, V _{REG} =2.8V
Input VSWR		< 2:1			
Output Load VSWR	10:1				No Damage.
Overall - TDMA					T=25°C, V_{CC} =3.4V unless otherwise speci- fied
Idle Current		250	500	mA	V _{MODE} =0V to 0.5V
TDMA Linear Efficiency	30	40		%	P _{OUT} =30dBm, V _{CC} =3.4V, V _{REG} =2.8V
TDMA ACP @ 30kHz		-29	-28	dBc	P _{OUT} =30dBm
TDMA ALT @ 60kHz		-49	-48	dBc	P _{OUT} =30dBm

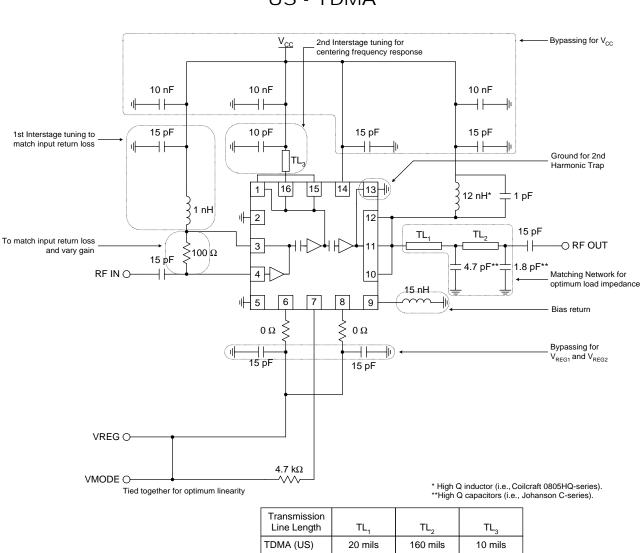
Devementer		Specification			Condition	
Parameter	Min.	Тур.	Max.	Unit	Condition	
Power Supply						
Power Supply Voltage	3.0	3.4	4.5	V		
V _{PD} Current		10		mA	Total pins 6 and 8	
V _{PD} and V _{MODE} Current		11	13	mA	Total pins 6, 7 and 8	
Turn On/Off time			100	ns		
Total Current (Power down)			10	μA	V _{PD} = low	
V _{PD} "Low" Voltage		0	0.2	V		
V _{PD} "High" Voltage	2.7	2.8	2.9	V		
MODE "High" Voltage	2.5	2.8		V	R1=1kΩ	
MODE "Low" Voltage		0	0.5	V	R1=1kΩ	
Stability		3:1			Inband	
		20:1			Outband	
Spurious		<-60		dBc		
Noise Power		-136		dBm/Hz	@ 80MHz offset	

Pin	Function	Description	Interface Schematic		
1	VCC2	Power supply for second stage and interstage match. Pins 1, 15 and 16 should be connected by a common trace where the pins contact the printed circuit board.			
2	immediately to ground plane for best performance. This ground should be isolated from the backside ground contact on top metal layer.				
3	VCC1	See pin 4.			
4	RF IN	RF input. An external 15pF series capacitor is required as a DC block and also provides for an input VSWR of <2:1 typical.	RF IN OFFICE STATES		
5	GND1	Ground for first stage. Keep traces physically short and connect imme- diately to ground plane for best performance. This ground should be isolated from the backside ground contact on top metal layer.	See pin 4.		
6	VPD1	Power Down control for first and second stages. When this pin is "low", all first and second stage circuits are shut off. When this pin is 2.8V, all first stage circuits are operating normally. V_{PD1} requires a regulated 2.8V for the amplifier to operate properly over all specified temperature and voltage ranges. A dropping resistor from a higher regulated voltage may be used to provide the required 2.8V.			
7	VMODE	For full power operation, MODE is set low. VMODE will reduce the bias current by up to 50% when set HIGH. Large Signal Gain is reduced approximately 1.5dB at 29dBm P_{OUT} and Small Signal Gain is reduced approximately 6dB. An external series resistor is optional to limit the amount of current required by the V_{MODE} pin.			
8	VPD2	Power Down control for the third stage. When this pin is "low", the third stage circuit is shut off. When this pin is 2.8V, the third stage circuit is operating normally. V_{PD} requires a regulated 2.8V for the amplifier to operate properly over all specified temperature and voltage ranges. A dropping resistor from a higher regulated voltage may be used to provide the required 2.8V. A 15pF high frequency bypass capacitor is recommended.			
9	BIAS GND	Requires a 15nH inductor.			
10	RF OUT	RF output and power supply for final stage. This is the unmatched col- lector output of the third stage. A DC block is required following the matching components. The biasing may be provided via a parallel L-C set for resonance at the operating frequency of 1850MHz to 1910MHz. It is important to select an inductor with very low DC resistance with a 1 A current rating. Alternatively, shunt microstrip techniques are also applicable and provide very low DC resistance. Low frequency bypass- ing is required for stability.	RF OUT		
11	RF OUT	Same as pin 12.	See pin 10.		
12	RF OUT	Same as pin 12.	See pin 10.		
13	2FO				
14	VCC	Supply for bias reference and control circuits. High frequency bypass- ing may be necessary.			
15	VCC2	Same as pin 1.			
16	VCC2	Same as pin 1.			
Pkg Base	GND	Ground connection. The backside of the package should be soldered to a top side ground pad which is connected to the ground plane with mul- tiple vias. The pad should have a short thermal path to the ground plane.			



Application Schematic Korea - CDMA

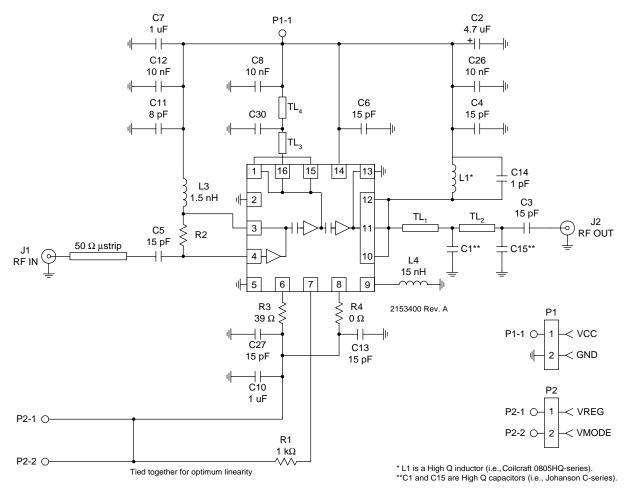




Application Schematic US - TDMA

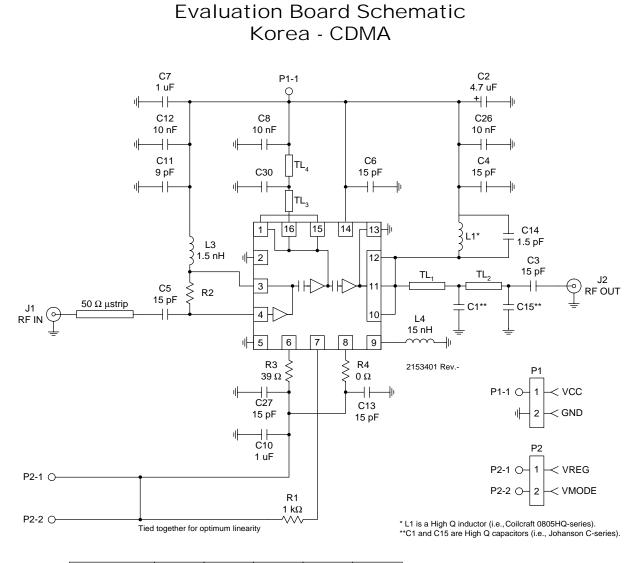
RF2153

Evaluation Board Schematic US - CDMA



Board	R2 (Ω)	C30 (pF)	C1 (pF)	L1 (nH)	C15 (pF)
CDMA (US)	150	10	4.7	12	2.2

Transmission Line Length	TL ₁	TL_2	TL ₃	TL_4
CDMA (US)	20 mils	100 mils	20 mils	100 mils or ≥ 2.7 nH inductor

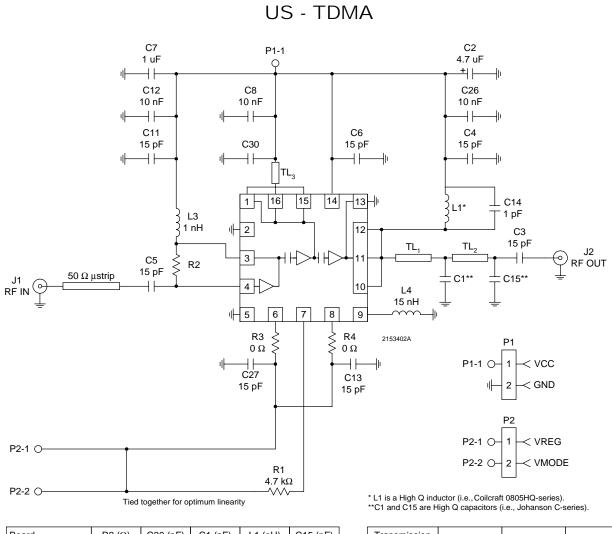


inductor

Board	R2 (Ω)	C30 (pF)	C1	(pF)	L1 (n⊦	ł)	C15 (pF)
CDMA (Korea)	180	11	5	5.6	12		2.2
	1						
Transmission Line Length	TL ₁	TL ₂		T	Έ_3		TL_4
CDMA (Korea)	30 mils	100 mi	ls	30	mils		100 mils r ≥ 2.7 nH

RF2153

Rev A17 000914



Evaluation Board Schematic

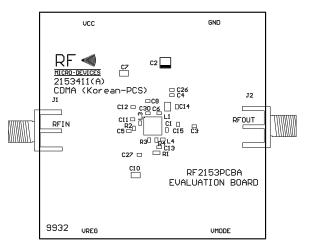
Board	R2 (Ω)	C30 (pF)	C1 (pF)	L1 (nH)	C15 (pF)
TDMA (US)	100	10	4.7	12	1.8

Transmission Line Length	TL ₁	TL ₂	TL ₃
TDMA (US)	20 mils	160 mils	10 mils

RF2153 Evaluation Board Layout US - CDMA Board Size 2.0" x 2.0" Board Thickness 0.031", Board Material FR-4 GND VCC RF •**** C2 C7 MICRO-DEVICES 2153410(B) CDMA (US-PCS) □ C26 □ C4 J2 .11 □C8 RFOUT L1 C11 🗆 RFIN 0^{C1}C15 C3 C5 20 C27 🗆 C10 RF2153PCBA EVALUATION BOARD

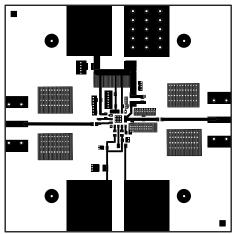
Evaluation Board Layout Korea - CDMA

VMODE



9932

VREG



8

Evaluation Board Layout US - TDMA

